



09/939 636

CofC

Docket No.: M4065.0477/P477
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Letters Patent of:
Kevin M. Devereaux

Patent No.: 6,753,547

Issued: June 22, 2004

For: METHOD AND APPARATUS FOR WAFER
LEVEL TESTING OF SEMICONDUCTOR
USING SACRIFICIAL ON DIE POWER
AND GROUND METALIZATION

Certificate
FEB 22 2005
of Correction

REQUEST FOR CERTIFICATE OF CORRECTION
PURSUANT TO 37 CFR 1.322

MS Post Issue
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Upon reviewing the above-identified patent, Patentee noted a typographical error which should be corrected.

In Claims:

Claim 10. The semiconductor wafer of claim 9 further comprising:

a Vss bonding pad coupled to the circuitry within said die for supplying a second voltage to said circuitry;

a sacrificial Vss bonding pad for supplying die (should be the) second voltage to the Vss bonding pad; and a sacrificial metal bus which connects the sacrificial Vss bonding pad and the Vss bonding pad.

The error was not in the application as filed by applicant; accordingly no fee is required.

Transmitted herewith is a proposed Certificate of Correction effecting such amendment. Patentee respectfully solicits the granting of the requested Certificate of Correction.

Dated: February 15, 2005

Respectfully submitted,

By 

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**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

PATENT NO. : 6,753,547
DATED : June 22, 2004
INVENTOR(S) : Kevin M. Devereaux

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Claim 10, line 5, "die" should read --the--.

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PATENT NO. 6,753,547

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